

Solder wire ISO-Core® “RA“, “RA-05“, “RA-AT“

Flux-cored, halide activated soft solder wire

Flux acc. DIN EN 29454.1, 1.1.2.B

or DIN EN 61190-1-3, ROM1

Standard solder wire for manual soldering in electrical engineering, standard flux content 2.5 %

Halogen content RA: 1.0%, RA-05: < 0.5%, RA-AT: 1.5%

Ø in mm 0.25 • 0.50 • 0.75 • 1.00 • 1.50 • 2.00 • 3.00 • 4.00

Spools 0.10 • 0.25 • 0.50 • 1.00 • 5.00 • 10.00 • 15.00 kg



Alloy	DIN EN ISO 9453	DIN EN 61190	Melting range	Lead-free/lead-containing
Sn95.5Ag3.8Cu0.7	S-Sn95Ag4Cu1	Sn96Ag04Cu0.7	217 °C eutectic	
Sn97Ag3	S-Sn97Ag3	-	221 - 224 °C	
Sn99.3Cu0.7	S-Sn99Cu1	Sn99Cu.7	227 °C eutectic	Lead-free
Sn97Cu3	S-Sn97Cu3	-	230 - 250 °C	
Sn100Ni+	S-Sn99Cu1 (NiGe)	Fuji Patent	227 °C eutectic	
Sn60Pb40	S-Sn60Pb40	Sn60Pb40	183 - 190 °C	
Sn60Pb38Cu2	S-Sn60Pb39Cu1	Sn60Pb38Cu02	183 - 190 °C	
Pb50Sn50	S-Pb50Sn50	Sn50Pb50	183 - 215 °C	Lead-containing
Pb60Sn40	S-Pb60Sn40	Sn40Pb60	183 - 235 °C	
Pb70Sn30	S-Pb70Sn30	Sn30Pb70	183 - 255 °C	

Further alloys are available in our electronic delivery program.

Solder wire ISO-Core® “Clear“

Flux-cored, lead-free soft solder wire

Flux acc. to DIN EN 29454.1, 1.2.2.B

or DIN EN 61190-1-3, REM1

High-quality solder wire for manual and mechanical soldering in electrical engineering, electromechanics and electronics.

Standard flux content 3.5 %

Thermally stable • spatter-free • optimum wetting effect • crystal clear residues

Ø in mm 0.25 • 0.50 • 0.75 • 1.00 • 1.50 • 2.00 • 3.00 • 4.00

Spools 0.10 • 0.25 • 0.50 • 1.00 • 5.00 • 10.00 • 15.00 kg



Alloy	DIN EN ISO 9453	DIN EN 61190	Melting range
Sn95.5Ag3.8Cu0.7	S-Sn95Ag4Cu1	Sn96Ag04Cu0.7	217 °C eutectic
Sn96.5Ag3Cu0.5	S-Sn96Ag3Cu1	Sn96Ag03Cu0.4	217 - 219 °C
Sn99.3Cu0.7	S-Sn99Cu1	Sn99Cu.7	227 °C eutectic
Sn100Ni+	S-Sn99Cu1 (NiGe)	Fuji Patent	227 °C eutectic

Further alloys are available in our electronic delivery program.

For fine soldering in electronics, electrical engineering as well as in telecommunications and electric motor construction

FELDER ISO-Core®- solder wires are produced similar to FELDER ISO-Tin®- electronic grade solder alloys using the same high-purity alloy components according to international standards. The fluxing agents are characterised by their high thermal stability and the fact that they do not spatter during reflow! The light, solid flux residue of the solder wires does not cause corrosion with nonferrous metals. As a result, they do not have to be removed from the soldered joint. Our RA-AT was especially developed for mechanical soldering with short cycle times and high soldering temperatures.